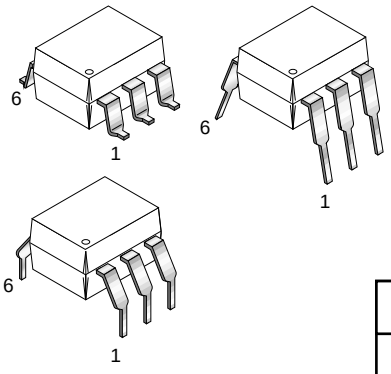
FAIRCHILD
SEMICONDUCTOR®

6-PIN DIP RANDOM-PHASE OPTOISOLATORS TRIAC DRIVER OUTPUT (250/400 VOLT PEAK)

MOC3010M MOC3011M MOC3012M MOC3020M MOC3021M MOC3022M MOC3023M

DESCRIPTION

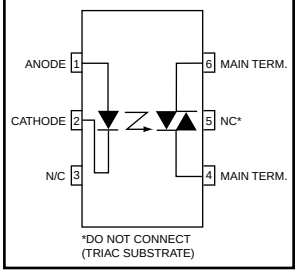
The MOC301XM and MOC302XM series are optically isolated triac driver devices. These devices contain a AlGaAs infrared emitting diode and a light activated silicon bilateral switch, which functions like a triac. They are designed for interfacing between electronic controls and power triacs to control resistive and inductive loads for 115/240 VAC operations.



FEATURES

- Excellent I_{FT} stability—IR emitting diode has low degradation
- High isolation voltage—minimum 5300 V_{AC} RMS
- Underwriters Laboratory (UL) recognized—File #E90700
- Peak blocking voltage
  -250V-MOC301XM
  -400V-MOC302XM
- VDE recognized (File #94766)
  -Ordering option V (e.g. MOC3023VM)

SCHEMATIC



APPLICATIONS

- European applications for
- Triac driver
  240 VAC (MOC302X only)
- Industrial controls
- Traffic lights
- Vending machines
- Solid state relay
- Lamp ballasts
- Solenoid/valve controls
- Static AC power switch
- Incandescent lamp dimmers
- Motor control

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C unless otherwise noted)

Parameters	Symbol	Device	Value	Units
TOTAL DEVICE Storage Temperature	T_{STG}	All	-40 to +150	°C
Operating Temperature	T_{OPR}	All	-40 to +85	°C
Lead Solder Temperature	T_{SOL}	All	260 for 10 sec	°C
Junction Temperature Range	T_J	All	-40 to +100	°C
Isolation Surge Voltage(1) (peak AC voltage, 60Hz, 1 sec duration)	V_{ISO}	All	7500	Vac(pk)
Total Device Power Dissipation @ 25°C	P_D	All	330	mW
Derate above 25°C			4.4	mW/°C
EMITTER Continuous Forward Current	I_F	All	60	mA
Reverse Voltage	V_R	All	3	V
Total Power Dissipation 25°C Ambient	P_D	All	100	mW
Derate above 25°C			1.33	mW/°C
DETECTOR Off-State Output Terminal Voltage	V_{DRM}	MOC3010M/1M/2M	250	V
		MOC3020M/1M/2M/3M	400	
Peak Repetitive Surge Current (PW = 1 ms, 120 pps)	I_{TSM}	All	1	V
Total Power Dissipation @ 25°C Ambient	P_D	All	300	mW
Derate above 25°C			4	mW/°C

Note

1. Isolation surge voltage, V_{ISO}, is an internal device dielectric breakdown rating. For this test, Pins 1 and 2 are common, and Pins 4, 5 and 6 are common.

ELECTRICAL CHARACTERISTICS (T_A = 25°C Unless otherwise specified)

INDIVIDUAL COMPONENT CHARACTERISTICS

Parameters	Test Conditions	Symbol	Device	Min	Typ	Max	Units
EMITTER							
Input Forward Voltage	I_F = 10 mA	V_F	All		1.15	1.5	V
Reverse Leakage Current	V_R = 3 V, T_A = 25°C	I_R	All		0.01	100	µA
DETECTOR							
Peak Blocking Current,Either Direction	Rated V_{DRM}, I_F = 0 (note 1)	I_{DRM}	All		10	100	nA
Peak On-State Voltage,Either Direction	I_{TM} = 100 mA peak, I_F = 0	V_{TM}	All		1.8	3	V
Critical Rate of Rise of Off-State Voltage	I_F = 0 (figure 5, note2)	dv/dt	All		10		V/µs

TRANSFER CHARACTERISTICS (T_A = 25°C Unless otherwise specified.)

DC Characteristics	Test Conditions	Symbol	Device	Min	Typ	Max	Units
LED Trigger Current	Voltage = 3V (note 3)	I_{FT}	MOC3020M			30	mA
			MOC3010M			15	
			MOC3021M				
			MOC3011M			10	
			MOC3022M				
			MOC3012M			5	
			MOC3023M				
Holding Current, Either Direction		I_H	All		100		µA

Note

1. Test voltage must be applied within dv/dt rating.
2. This is static dv/dt. See Figure 5 for test circuit. Commutating dv/dt is a function of the load-driving thyristor(s) only.
3. All devices are guaranteed to trigger at an I_F value less than or equal to max I_{FT}. Therefore, recommended operating I_F lies between max I_{FT} (30 mA for MOC3020M, 15 mA for MOC3010M and MOC3021M, 10 mA for MOC3011M and MOC3022M, 5 mA for MOC3012M and MOC3023M) and absolute max I_F (60 mA).

Fig. 1 LED Forward Voltage vs. Forward Current

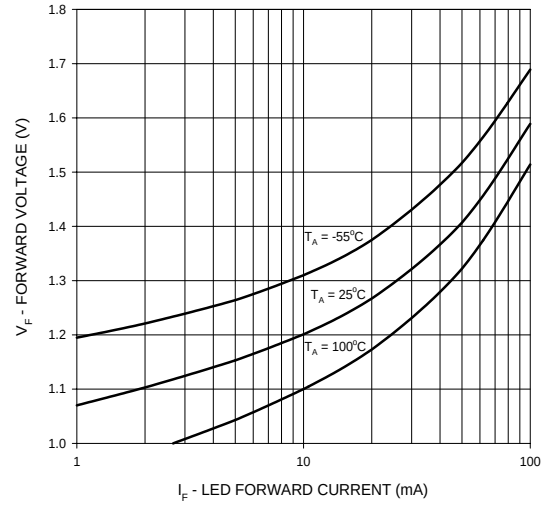


Fig. 2 On-State Characteristics

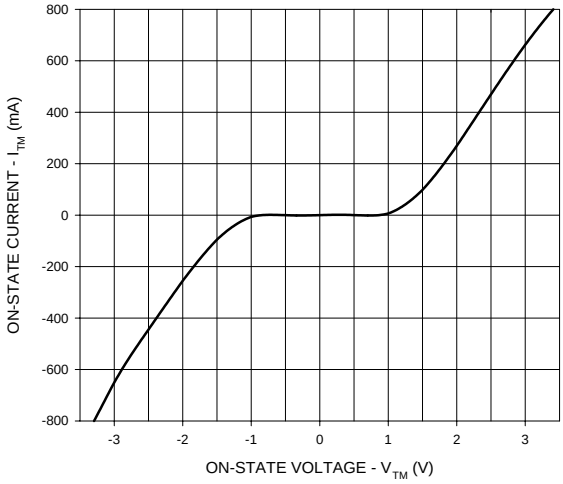


Fig. 3 Trigger Current vs. Ambient Temperature

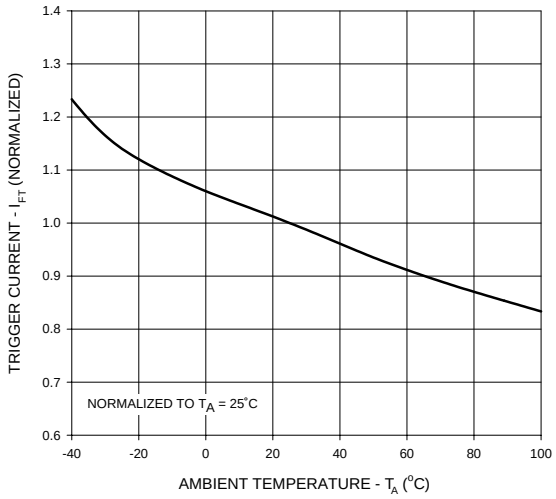


Fig. 4 LED Current Required to Trigger vs. LED Pulse Width

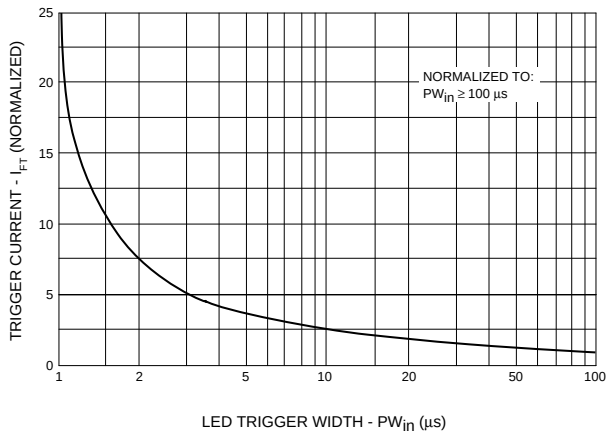


Fig. 5 dv/dt vs. Temperature

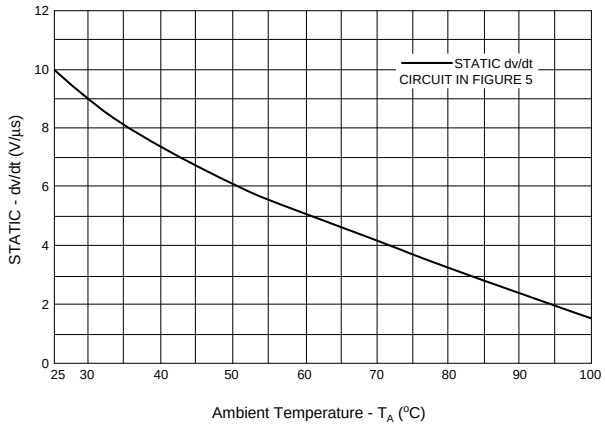
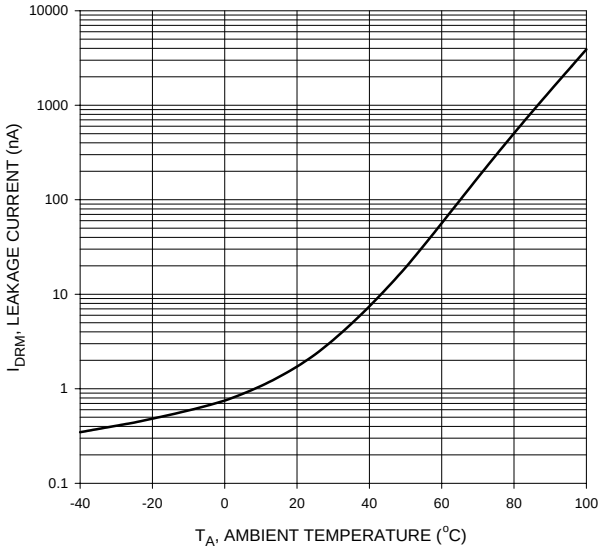
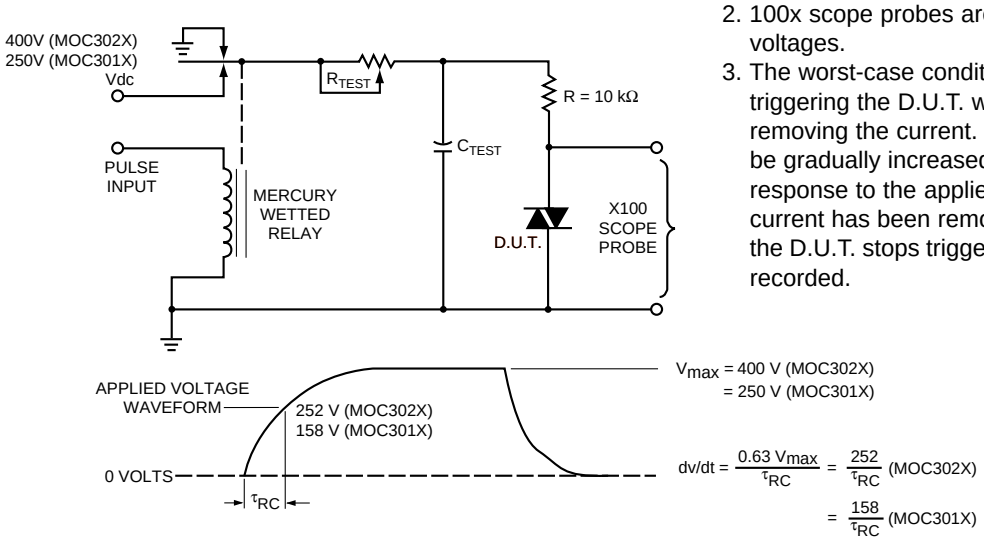


Fig. 6 Leakage Current, I_{DRM} vs. Temperature





1. The mercury wetted relay provides a high speed repeated pulse to the D.U.T.
2. 100x scope probes are used, to allow high speeds and voltages.
3. The worst-case condition for static dv/dt is established by triggering the D.U.T. with a normal LED input current, then removing the current. The variable R_{TEST} allows the dv/dt to be gradually increased until the D.U.T. continues to trigger in response to the applied voltage pulse, even after the LED current has been removed. The dv/dt is then decreased until the D.U.T. stops triggering. τ_{RC} is measured at this point and recorded.

Figure 5. Static dv/dt Test Circuit

NOTE: This optoisolator should not be used to drive a load directly.
It is intended to be a trigger device only.

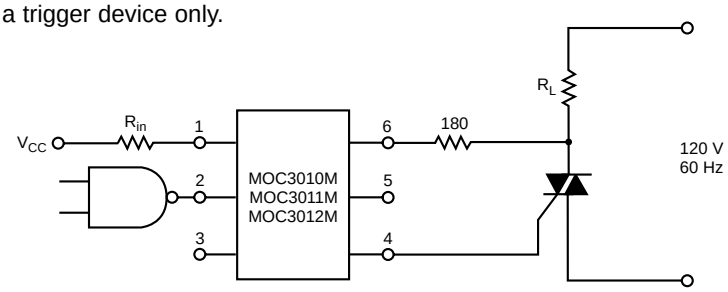


Figure 6. Resistive Load

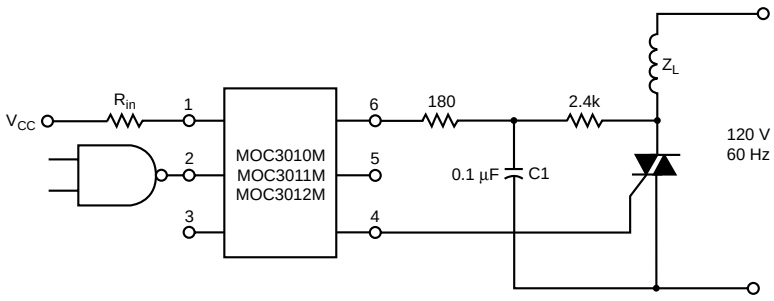


Figure 7. Inductive Load with Sensitive Gate Triac ($I_{GT} \leq 15$ mA)

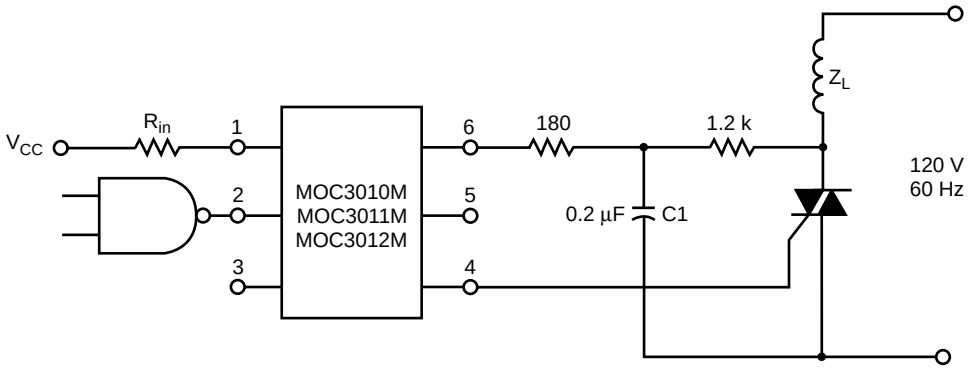
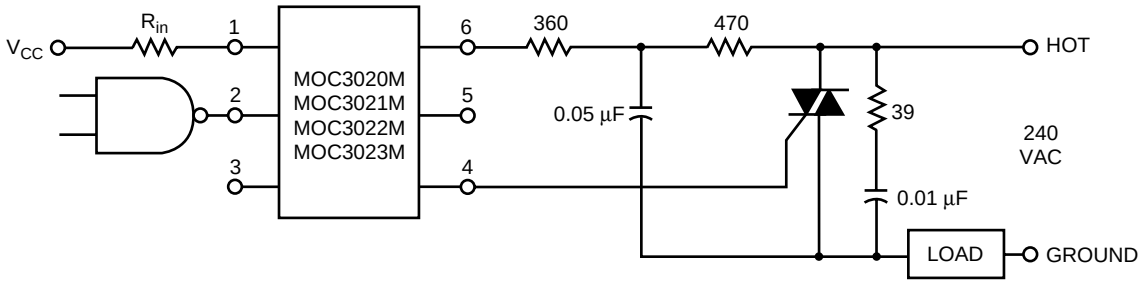


Figure 8. Inductive Load with Sensitive Gate Triac ($I_{GT} \leq 15$ mA)



In this circuit the “hot” side of the line is switched and the load connected to the cold or ground side.

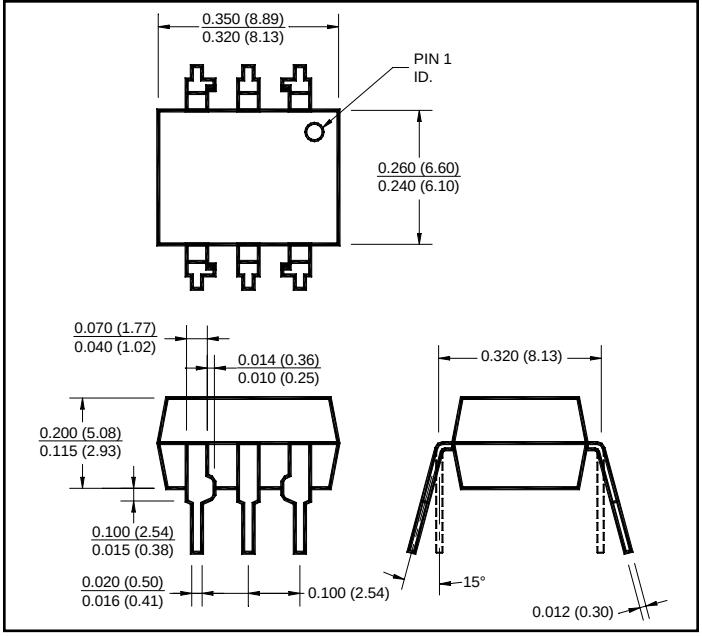
The 39 ohm resistor and 0.01 µF capacitor are for snubbing of the triac, and the 470 ohm resistor and 0.05 µF capacitor are for snubbing the coupler. These components may or may not be necessary depending upon the particular and load used.

Figure 9. Typical Application Circuit

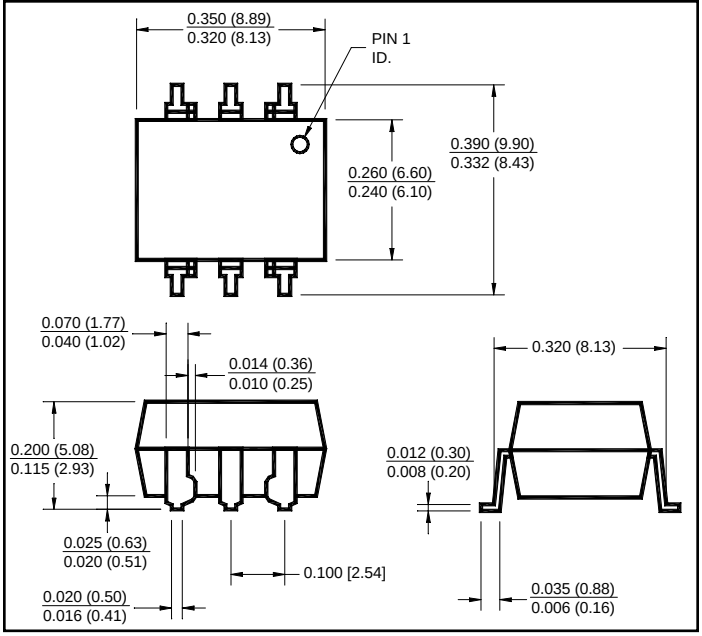
6-PIN DIP RANDOM-PHASE OPTOISOLATORS TRIAC DRIVER OUTPUT (250/400 VOLT PEAK)

MOC3010M MOC3011M MOC3012M MOC3020M MOC3021M MOC3022M MOC3023M

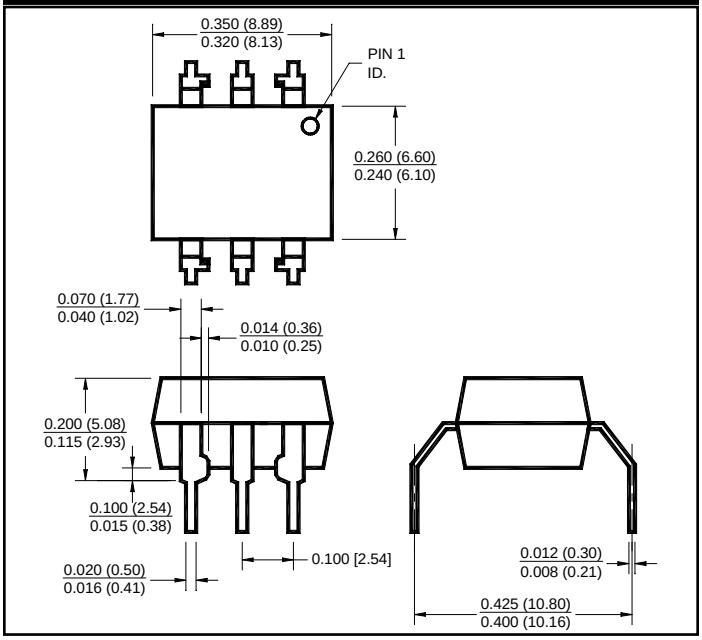
Package Dimensions (Through Hole)



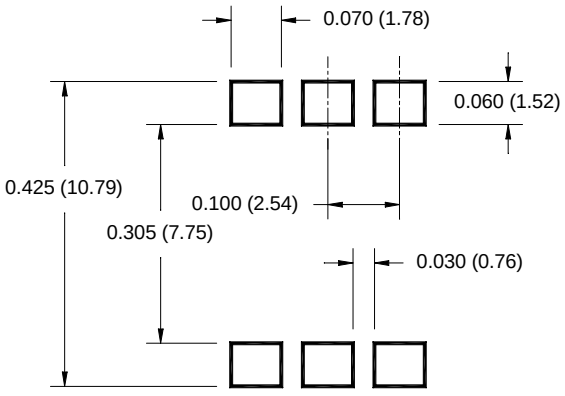
Package Dimensions (Surface Mount)



Package Dimensions (0.4”Lead Spacing)



Recommended Pad Layout for Surface Mount Leadform



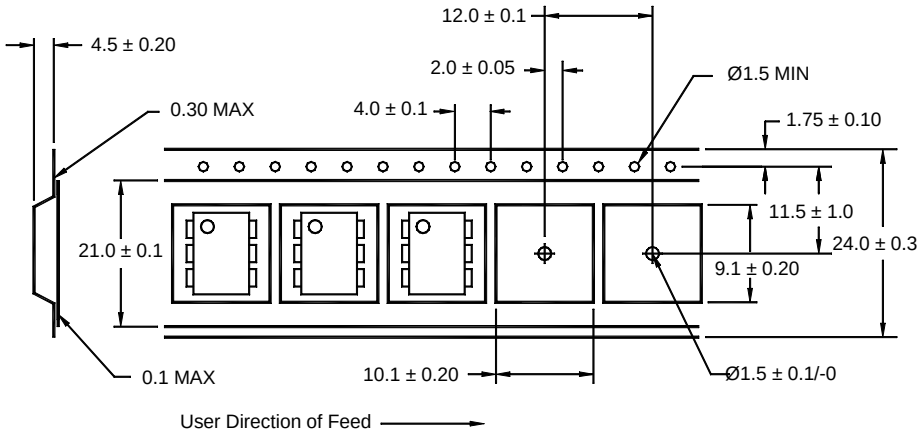
NOTE

All dimensions are in inches (millimeters)

ORDERING INFORMATION

Option	Order Entry Identifier	Description
S	S	Surface Mount Lead Bend
SR2	SR2	Surface Mount; Tape and reel
T	T	0.4” Lead Spacing
V	V	VDE 0884
TV	TV	VDE 0884, 0.4” Lead Spacing
SV	SV	VDE 0884, Surface Mount
SR2V	SR2V	VDE 0884, Surface Mount, Tape & Reel

QT Carrier Tape Specifications (“D” Taping Orientation)



NOTE

All dimensions are in inches (millimeters)

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